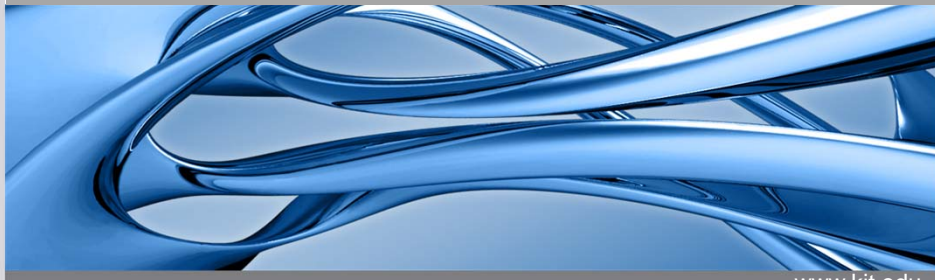


## A new high performance micro wave plasma source

S. Ulrich, J. Ye, M. Stüber, H. Leiste

robeko in-house exhibition & workshop plasmatechnology, 30<sup>th</sup> September 2015

Institute for Applied Materials (IAM-AWP), Department of Composites and Thin Films



[www.kit.edu](http://www.kit.edu)

## Outline

- Introduction & motivation
- High rate deposition of a-C:H with a microwave plasma source
- Deposition of coatings in the system Ti-C with HiPIMS
- Hybrid technology: HiPIMS/DC magnetron sputtering,  
HiPIMS/ microwave plasma source deposition
- Summary and outlook



- **Introduction & motivation**

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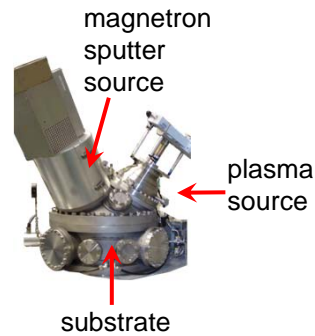
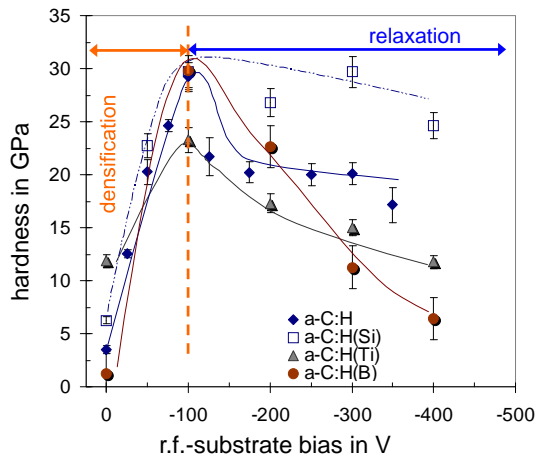
**Introduction & motivation**

**High performance plasma sources can be used for:**

- High-rate Ar ion etching
- The addition of nitrogen, carbon or oxygen ions and radicals
- Plasma nitriding or plasma oxidation
- High rate deposition of a-C:H and ta-C:H
- Developing PVD/PECVD hybrid processes
- High rate deposition of carbon-based low friction nanocomposites

## Introduction & motivation

### Modified a-C:H coatings produced by a PECVD/PVD hybrid process



S. Ulrich, H. Holleck, H. Leiste, L. Niederberger, E. Nold, K. Sell, M. Stüber, J. Ye, C. Ziebert, P. Pesch, S. Sattel, Nano-scale, multi-functional coatings in the material system B-C-N-H, Surf. Coat. Technol. 200 1-4 (2005) 7-13

- Independent particle fluxes forming a-C:H and adding Si, Ti or B

## Introduction & motivation

### HiPIMS

Pulsing allows us to use high peak power while keeping the average power relatively low, making it easy on power grid demands while reaching technologically interesting plasma states.

#### Advantages:

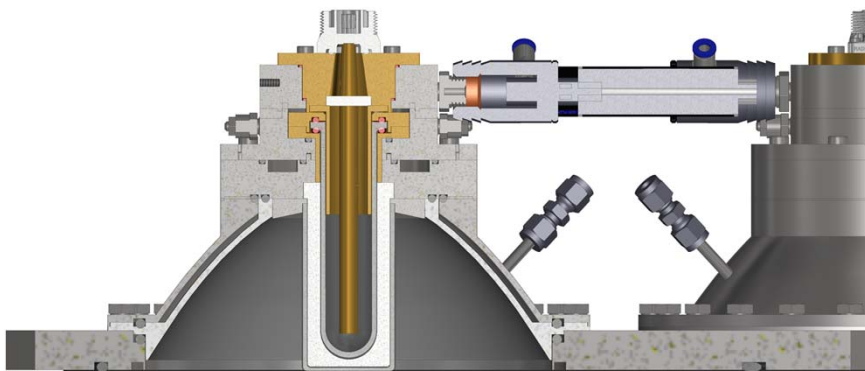
- film forming particles: ions
- control of growth process
- interface design is possible
- high adhesion
- compact morphology

#### Disadvantages:

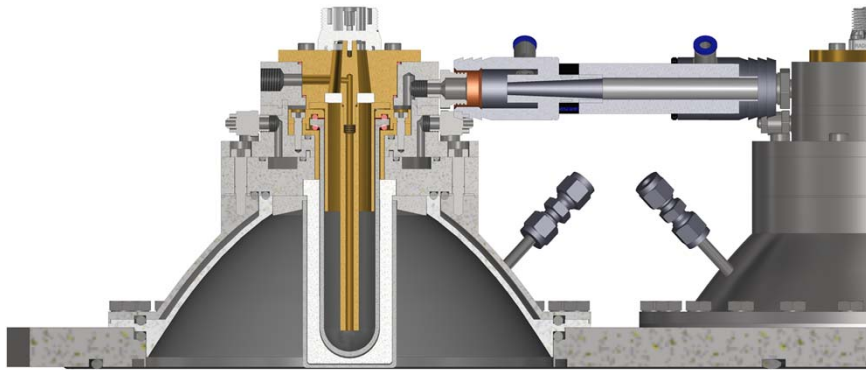
- redeposition process on target
- low growth rate
- arcing poisoning problems

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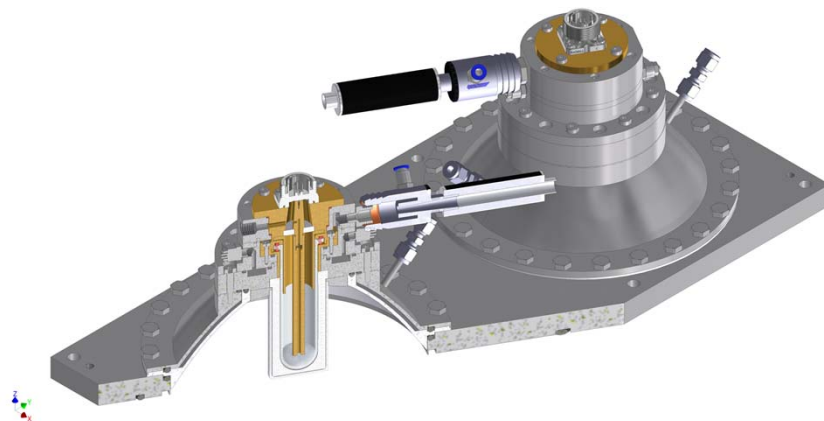
## Experimental details



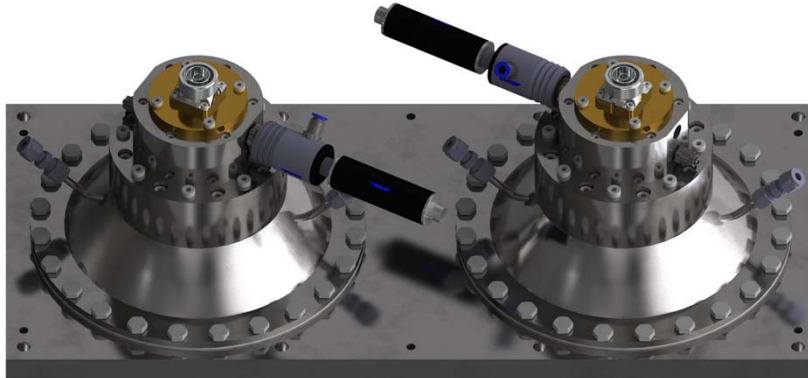
Experimental details



Experimental details



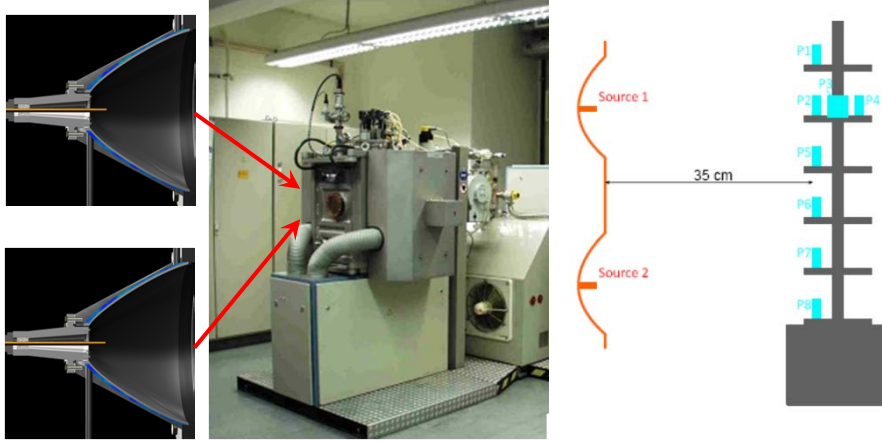
## Experimental details



## Experimental details

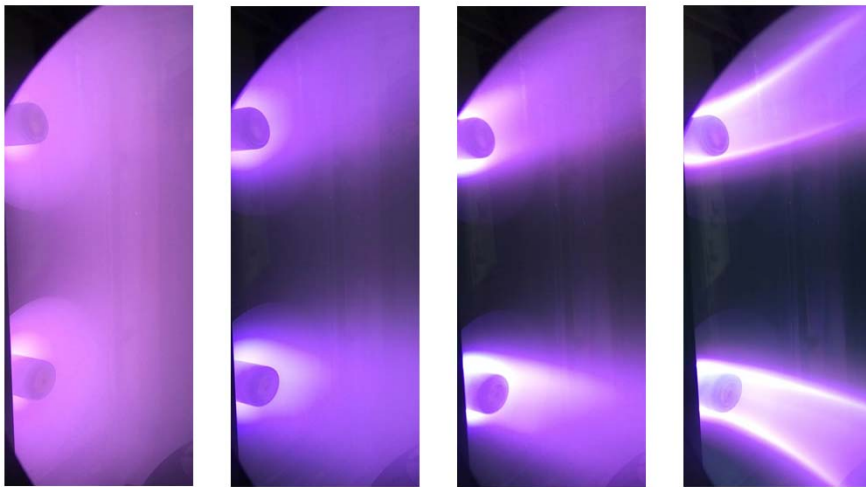


## Experimental details

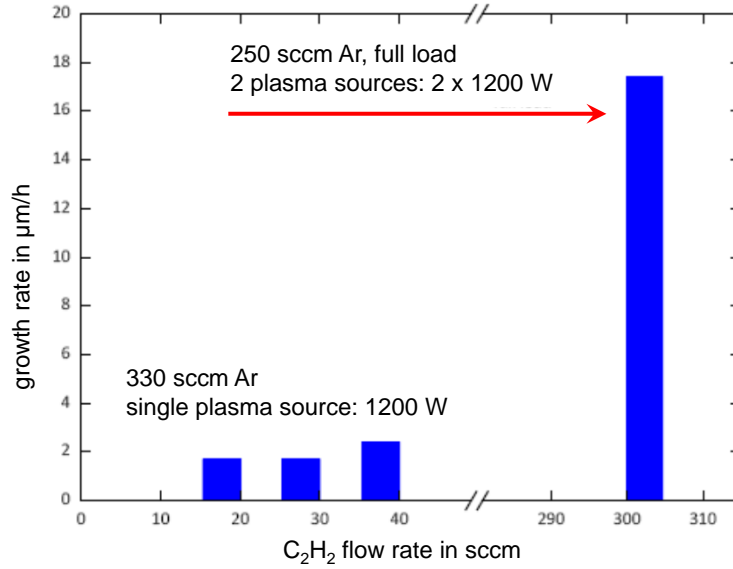


Developments in PVD/PECVD coatings for automotive applications  
R. Tietema, R. Jacobs, D. Doerwald, I. Kolev, J. Landsbergen  
IHI Hauzer Techno Coating BV, AEPSE, 22-WS-6

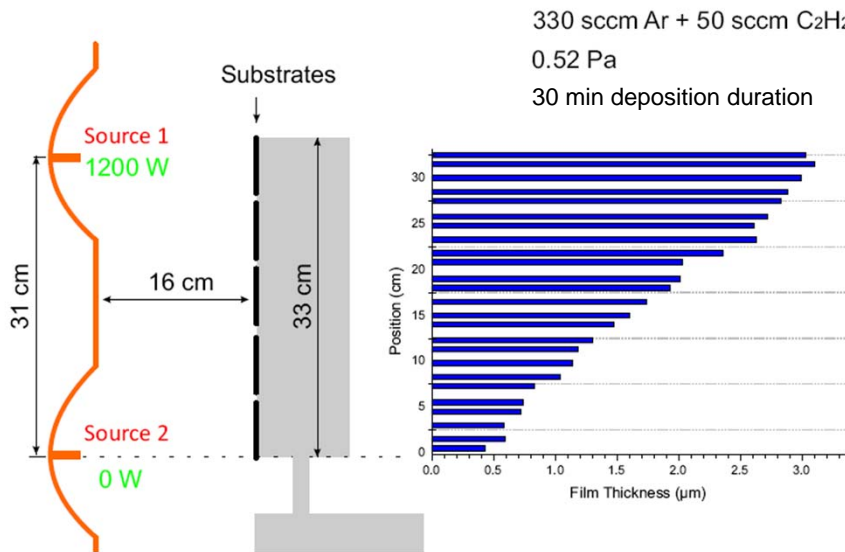
## Experimental details



**Selected results: variation of C<sub>2</sub>H<sub>2</sub> flow rate**

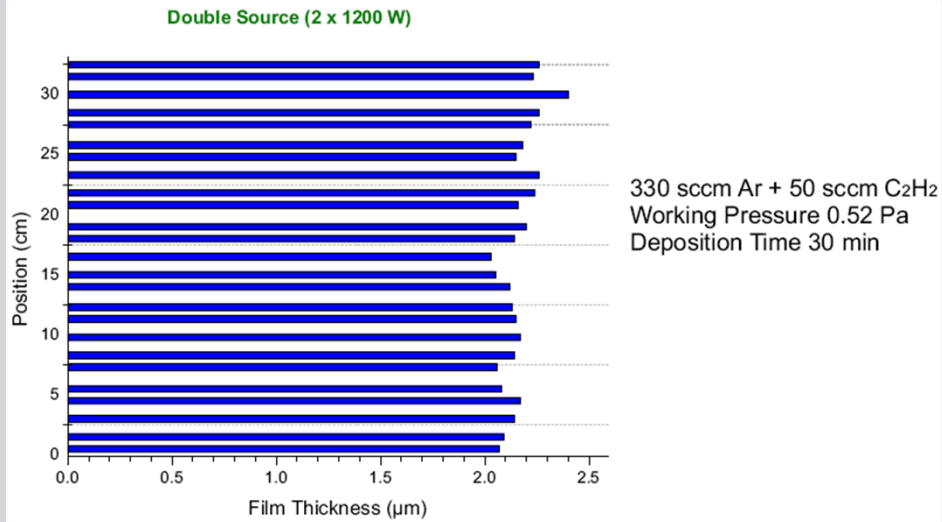


**Selected results: thickness profile using 1 source**

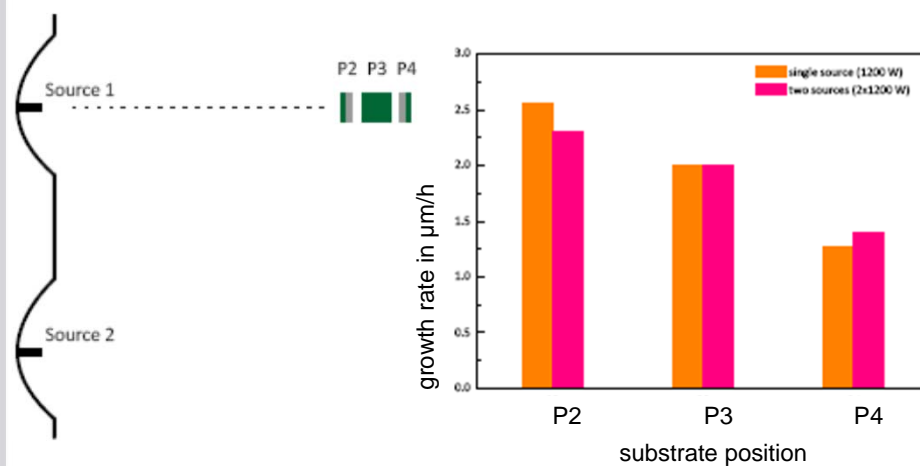




### Selected results: homogeneity

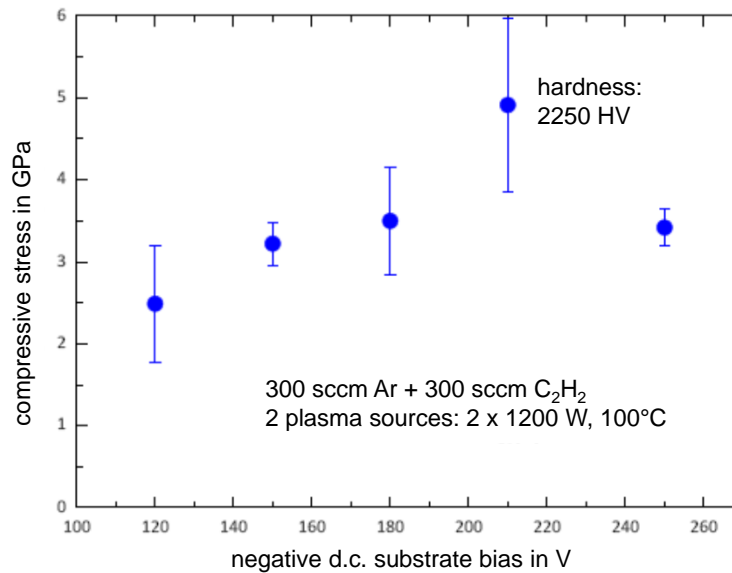


### Selected results: homogeneity



homogeneity single source operation:  $R(P4) = 50\% R(P2)$   
 homogeneity 2 sources operation:  $R(P4) = 66\% R(P2)$

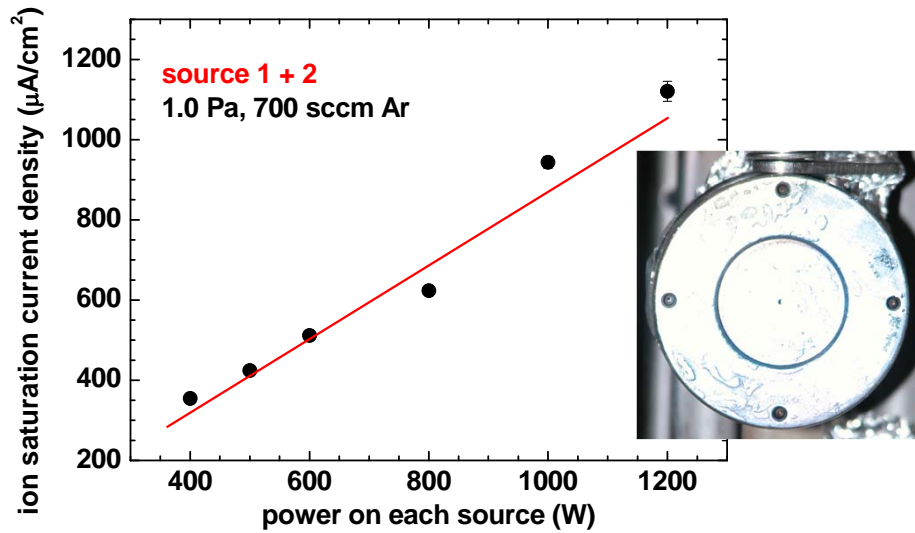
### Selected results: residual stress



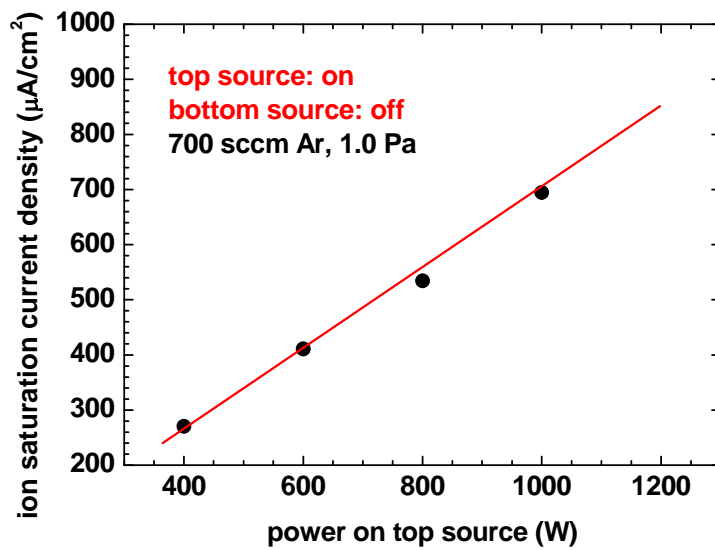
### Selected results: high growth rate

- Deposition with **single plasma source**  
(new BN-part attached on antenna): 1 x 1.4kW
- Gas: **500 sccm C<sub>2</sub>H<sub>2</sub> + 15 sccm Ar**
- Pressure: (a) before deposition  $1.2 \times 10^{-2}$  mbar,  
(b) during deposition (plasma on)  **$5.4 \times 10^{-3}$  mbar**
- Without substrate bias, no substrate rotation during deposition
- Distance** between substrate and plasma-source: ca. **20 cm**
- Deposition time: 28 min
- Film thickness: 16.7  $\mu\text{m}$
- Chamber temperature: 47° C in the end of deposition
- Muegge 3-stub tuner: no need for adjustment during deposition,  
power reflection kept at 0 - 2%.  
Tuner temperature 32° C in the end of deposition
- Deposition rate: 35.8  $\mu\text{m/h}$**

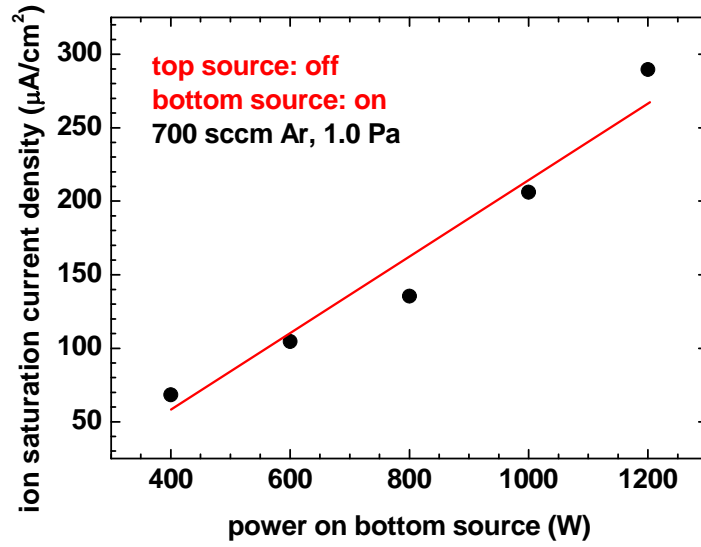
Selected results: plasma diagnostics



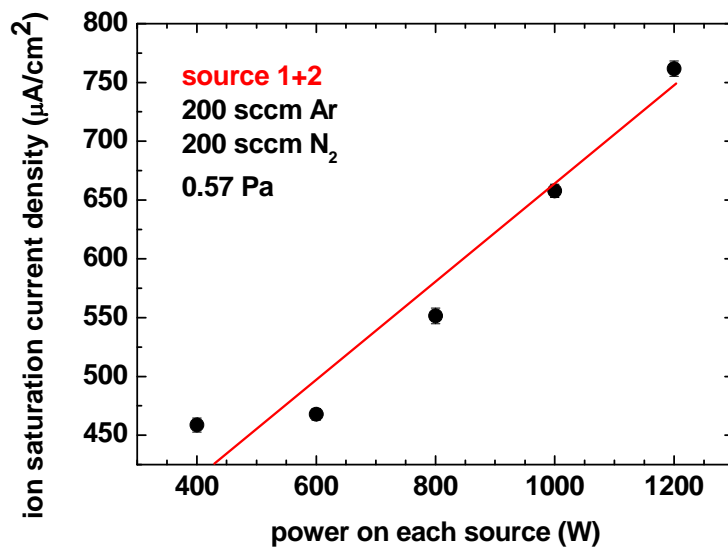
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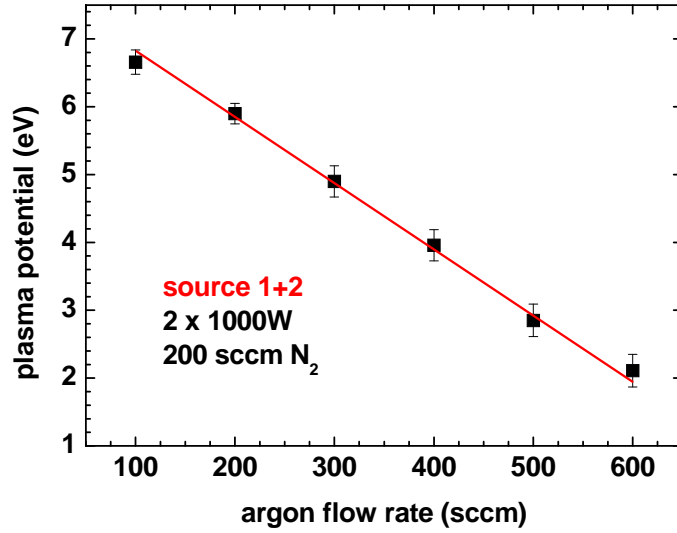
Selected results: plasma diagnostics



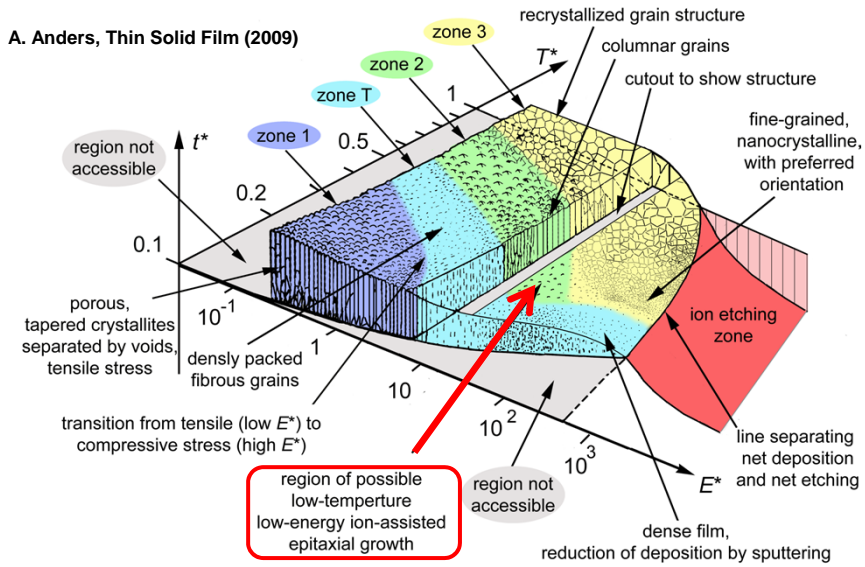
Selected results: plasma diagnostics



### Selected results: plasma diagnostics



### Application: low ion energy in combination with high ion current densities



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## Deposition of coatings in the system Ti-C with HiPIMS



### PVD Hauser

Ti-target  
planar magnetron  
dimension: 125 mm x 406 mm  
area: 507,5 cm<sup>2</sup>

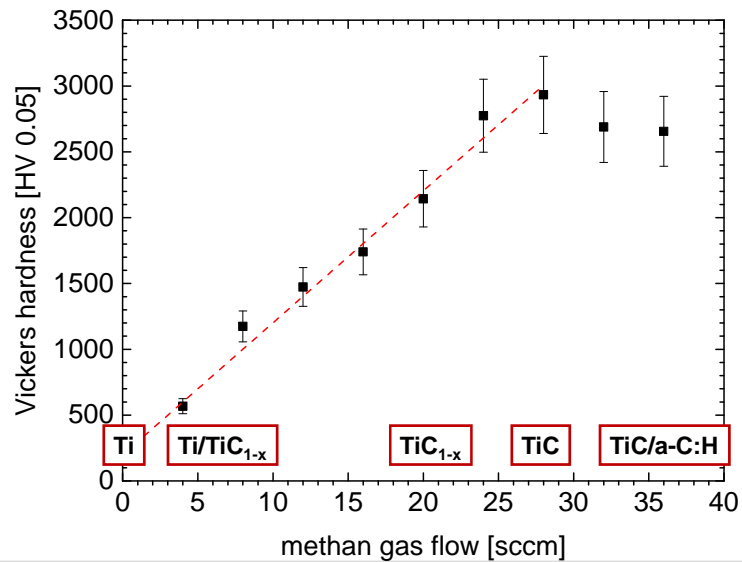
### CABINET MELEC

DUAL – CHANNEL  
DC PULSE POWER SUPPLY SET  
A: +/-1000V / +/- 500A ; 5 kW DC power  
B: +/-1000V / +/- 500A; 5 kW DC power  
4 channel measurement 2 x U(t); 2 x I(t)  
Diode module using DC – HiPIMS (UP)

### 5 kW DC AVERAGE CONST

HiPIMS : DC = 100% : 0%

## Deposition of coatings in the system Ti-C with HiPIMS



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**PVD Hauser**

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planar magnetron

dimension: 125 mm x 406 mm

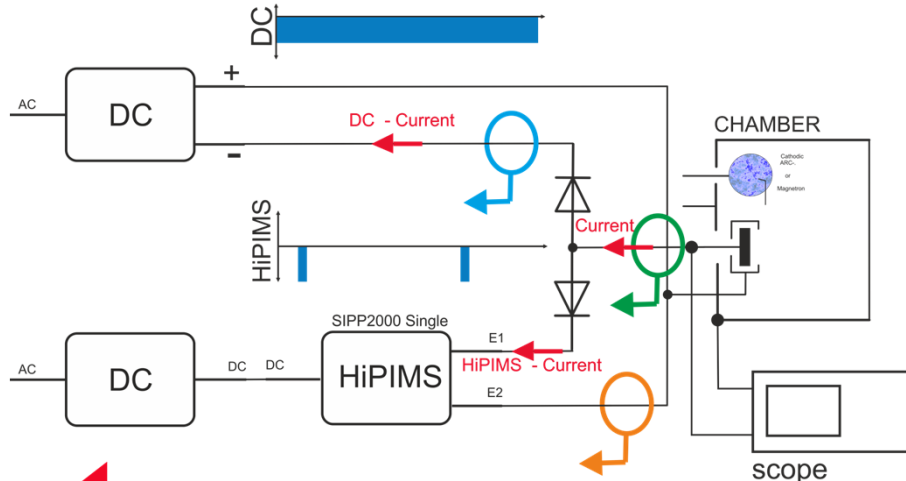
area: 507,5 cm<sup>2</sup>

**5 kW DC AVERAGE CONST**

HiPIMS : DC = 100% : 0%

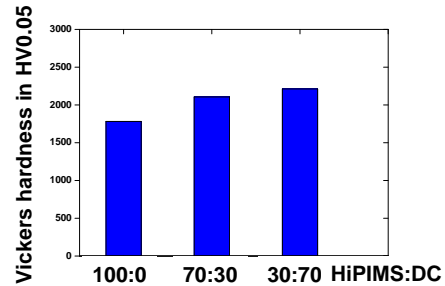
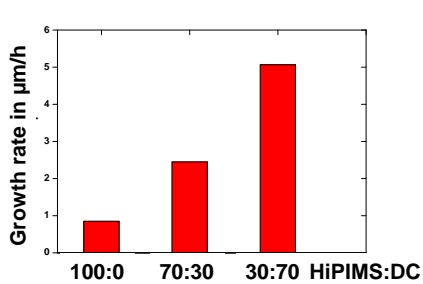
HiPIMS : DC = 70% : 30%

HiPIMS : DC = 30% : 70%



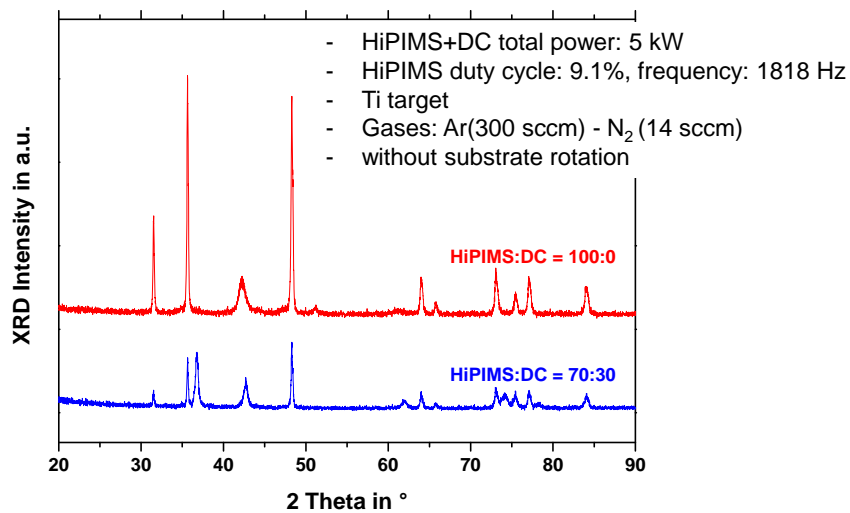


## Hybrid technology: HiPIMS/DC magnetron sputtering: Ti-N

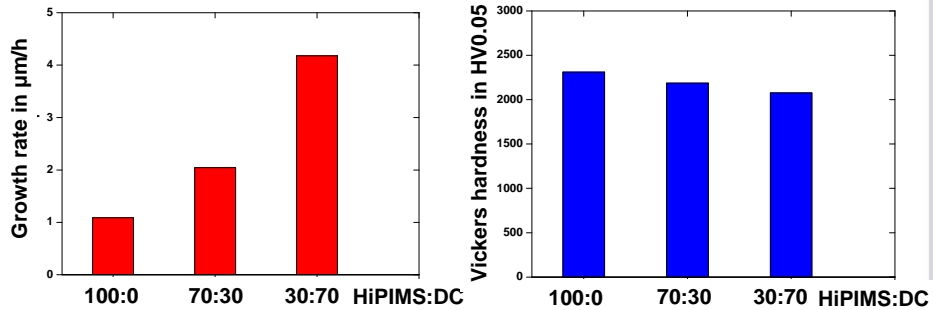


- HiPIMS+DC total power: 5 kW
- HiPIMS duty cycle: 9.1%, frequency: 1818 Hz
- Ti target
- Working gas: Ar(300 sccm) – reactive gas: N<sub>2</sub> (14 sccm)
- without substrate rotation

## Hybride technology: HiPIMS/DC magnetron sputtering: Ti-N

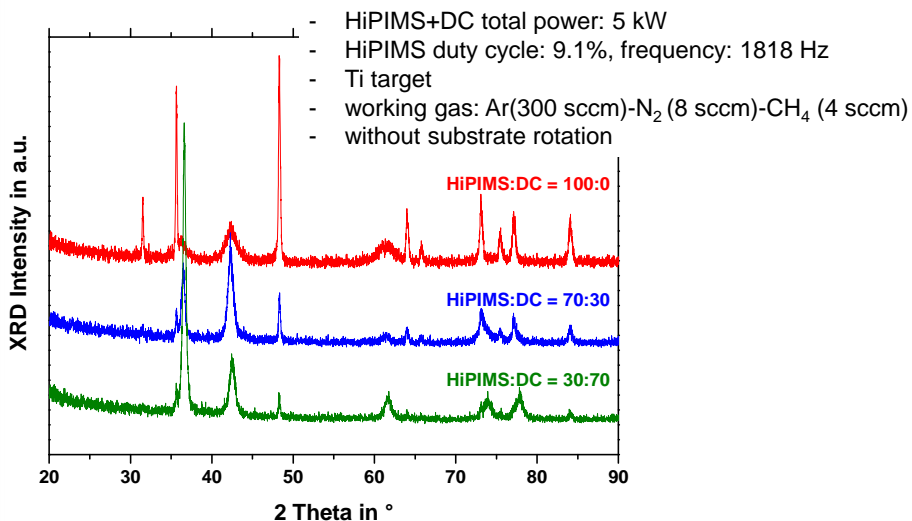


## Hybrid technology: HiPIMS/DC magnetron sputtering: Ti-C-N

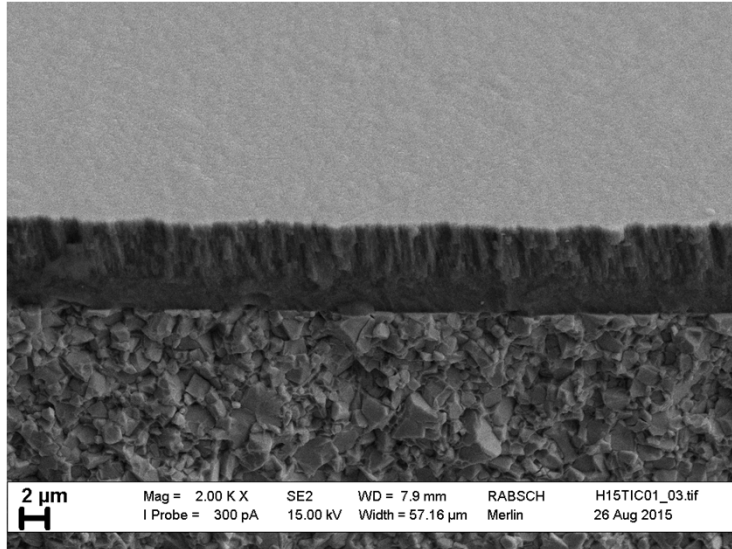


- HiPIMS+DC total power: 5 kW
- HiPIMS duty cycle: 9.1%, frequency: 1818 Hz
- Ti target
- working gas: Ar (300 sccm) – reactive gases:  $\text{N}_2$  (8 sccm) -  $\text{CH}_4$  (methan: 4 sccm)
- without substrate rotation

## Hybrid technology: HiPIMS/DC magnetron sputtering: TI-C-N



## Hybrid technology: HiPIMS/ micro wave plasma source Ti-C



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- **Summary and outlook**

### Summary – a-C:H (MW plasma)



- successful integration of 2 plasma sources in Hauzer coating facility
- - stable operation (in time, variation of load, ...)
- hardness (300 sccm Ar, 40 sccm C<sub>2</sub>H<sub>2</sub>, -80 V substrate bias) = 2600 HV
- operation with 100% C<sub>2</sub>H<sub>2</sub> possible
- commercial available Hauzer facility: 1200 W, 100% C<sub>2</sub>H<sub>2</sub>, 700 sccm C<sub>2</sub>H<sub>2</sub>, 36 μm/h, 6 μm/h with 2-fold rotation
- low plasma potential between 2 eV and 10 eV
- ion current densities of 1 mA/cm<sup>2</sup> at large distances

### Summary – Ti-N, Ti-C-N (Hybrid technology: HiPIMS/DC)



- Increasing of growth rate HiPIMS/DC using mixed mode by a factor of 5 for Ti-N and 4 for Ti-C-N compared to HiPIMS only
- Hardness and microstructure is nearly not effected
- New way of process optimization HiPIMS/DC graded coatings e. g. interface design, design of nucleation and growth phase
- HiPIMS/DC is an evolving technology with high potential concerning depositions rate, film properties and structural design
- HiPIMS can be performed in bipolar mode, improved process stability, arc prevention (pulse package mode), control of residual stress , mechanical properties

### Summary – Ti-C (Hybrid technology: HiPIMS/MW plasma)

- successful deposition of coatings in the system Ti-C by HiPIMS and HiPIMS/microwave plasma source
- Stable process conditions

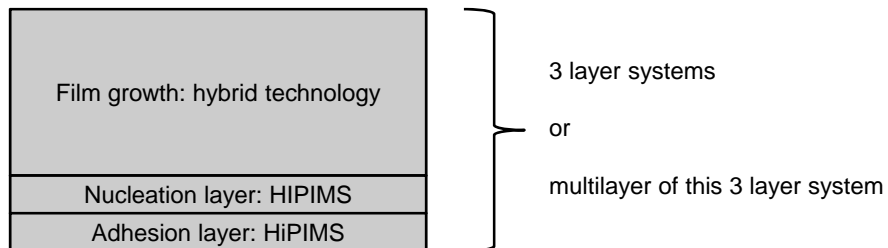
## Outlook



### Hybrid technology:

HiPIMS/DC magnetron sputtering + MW plasma source deposition  
for carbon based coating systems

### New coating concepts when HiPIMS is involved



## Many thanks ...



... to my co-workers **J. Ye, M. Stüber and H. Leiste**

... to my technical staff: **S. Schweiger, B. Rabsch, K. Erbes**

... to our distribution partner **robeko**

... and **Rolf Schäfer** for the invitation

**Thank you very much  
for your attention!**

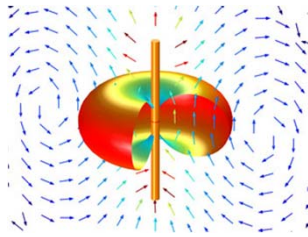


## Experimental details: modelling tools

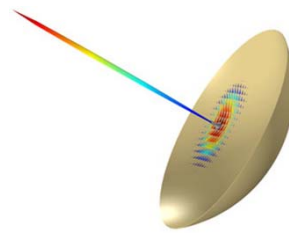


### COMSOL

RF Module  
Software for Microwave and RF Design



*Modeling a Dipole Antenna*



*Parabolic Reflector Antenna*

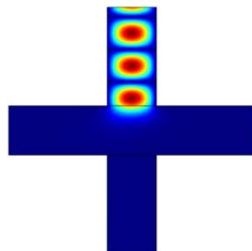
<https://www.comsol.pt/>

## Experimental details: modelling tools



### COMSOL

Plasma Module  
Software for Modeling Low-Temperature, Non-Equilibrium Discharges



*In-Plane Microwave Plasma*

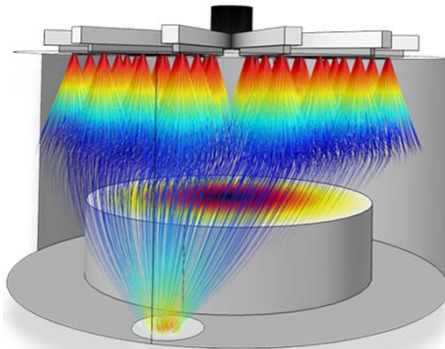
<https://www.comsol.pt/>

## Experimental details: modelling tools



### COMSOL

Particle Tracing Module  
Software for Studying the Interaction between Particles and Fields



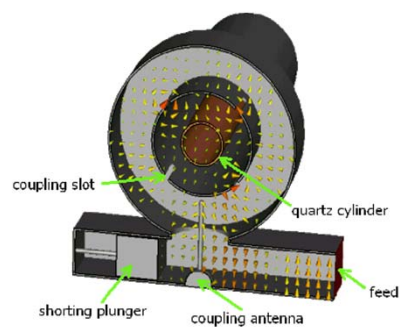
*Particles are injected from a system of injection nozzles into a CVD chamber with a cone angle of 15 degrees. Initially they have enough inertia to follow their original trajectory but ultimately the drag force takes over and the particles begin to follow the background gas out of the exhaust port.*

<https://www.comsol.pt/>

## Experimental details: modelling tools



### CST STUDIO SUITE



*Cross section of a microwave plasma source*

<https://www.cst.com/Products/CSTS2>